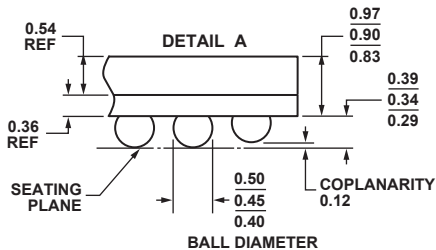
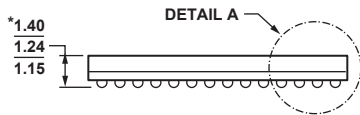
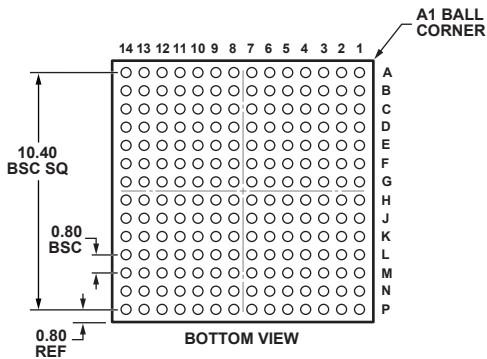
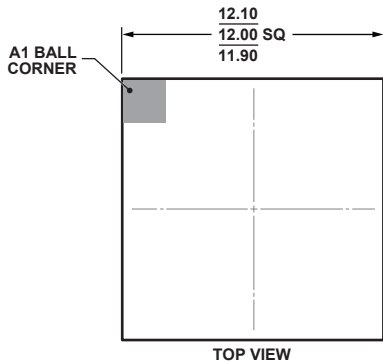


**196-Ball Chip Scale Package Ball Grid Array [CSP\_BGA]  
(BC-196-9)**

Dimensions shown in millimeters



\*COMPLIANT TO JEDEC STANDARDS MO-219 WITH  
EXCEPTION TO PACKAGE HEIGHT.